

A<sup>1</sup>  
prevent the heat applied to the engaging portions 2a from radiating via the heat radiating plate, and thus the soldering operation can be easily performed.--.

Page 5, replace the paragraph, beginning on line 1, as follows:

A<sup>2</sup>  
--Then, the surface of the printed wiring board 20 which is formed with the copper foil lands 23 and the copper foil pattern 26 is dipped in the melting nolead solder in the solder tank of the soldering device (not shown) for a predetermined time period. By this, the terminals 14 of the three-terminal regulator 13 are soldered to the copper foil pattern 26, and the legs 11 of the heat radiating plate 50 are soldered to the copper foil lands 23.--;

replace the paragraph, beginning on line 8, as follows:

A<sup>3</sup>  
--When the legs 11 of the heat radiating plate 50 are heated by being dipped into the nolead solder tank, the heat radiating plate 50 radiates the heat from the body unit 10 (i.e., the main plate 10a and the side plates 10b). However, according to the heat radiating plate 50 of the present invention, since the slits 12 are formed adjacent to the legs 11, the heat radiation effect by the legs 11 are quite small, and the temperature decrease of the nolead solder around the legs 11 can be suppressed to a minimum degree. Therefore, as shown in FIG.

A3 2, the heat radiating plate 50 is securely soldered to the copper foil lands 23.--.

Page 6, replace the paragraph, beginning on line 12, as follows:

A4 --When the printed wiring board 24 to which the bus bar 60 thus configured is attached is dipped into the nolead solder tank, the slits 18 suppress the temperature decrease of the nolead solder around the legs 17. Therefore, the legs 11 are securely soldered to the copper foil lands of the printed wiring board 24.--;

replace the paragraph, beginning on line 28, as follows:

A5 --As described above, the present invention provides parts suitable for mass production and securely soldered to a print wiring board by a solder dipping device that uses nolead solder having high melting point.--.

IN THE CLAIMS:

Cancel claims 1-7.

Add the following new claims:

A6 --8. (new) A part comprising a plate having a leg thereon and a slit beside the leg, the slit extending in the same direction as the leg, the leg being longer than the plate on the side of the slit opposite the leg.